IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Honchin EN et al.

Appln. No. Based on

PCT/JP99/05003

Group Art Unit: Unassigned

Confirmation No.: Unknown

Examiner: Unassigned

Filed: March 14, 2001

For: PRINTED WIRING BOARD AND

March 14, 2001

ITS MANUFACTURING METHOD

PRELIMINARY AMENDMENT

Commissioner for Patents Washington, D.C. 20231

Sir:

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Prior to examination, please amend the above-identified application as follows:

IN THE CLAIMS:

Please enter the following amended claims:

- 17. The electroless plating solution according to Claim 14, the temperature of which is 25 to 40°C.
- 18. The electroless plating solution according to Claim 14 wherein the copper deposition rate of said electroless plating solution is 1 to 2 μ m/hour.